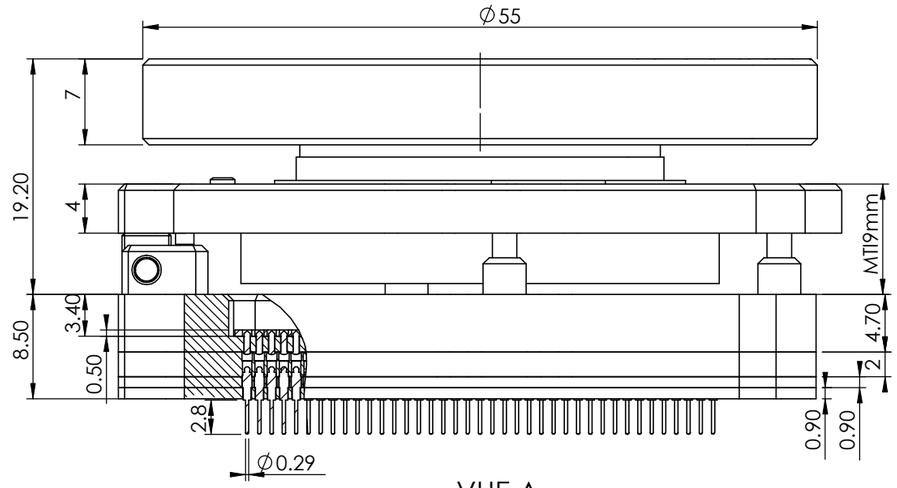
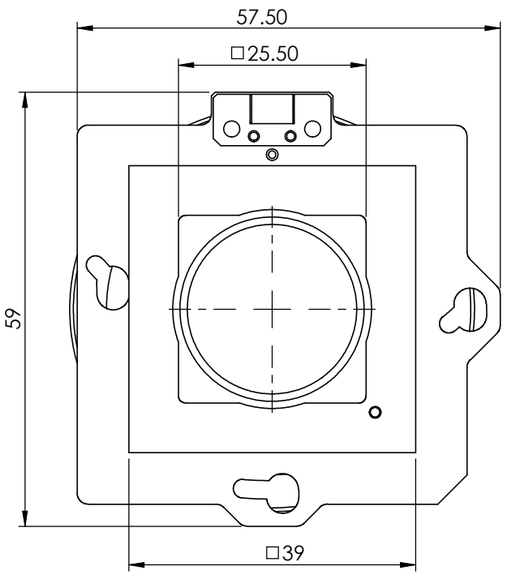
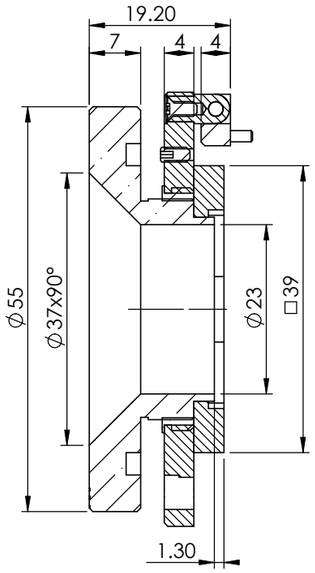
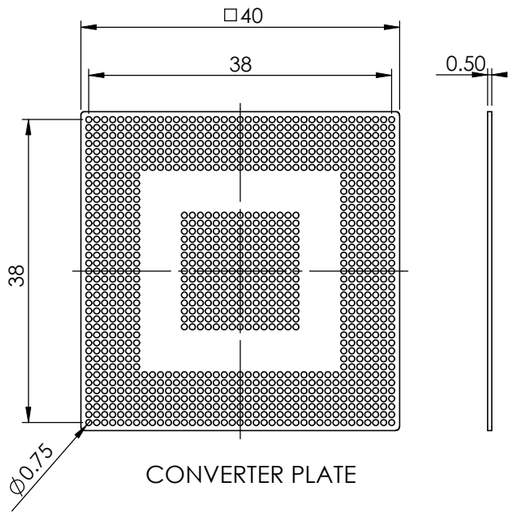


VUE A

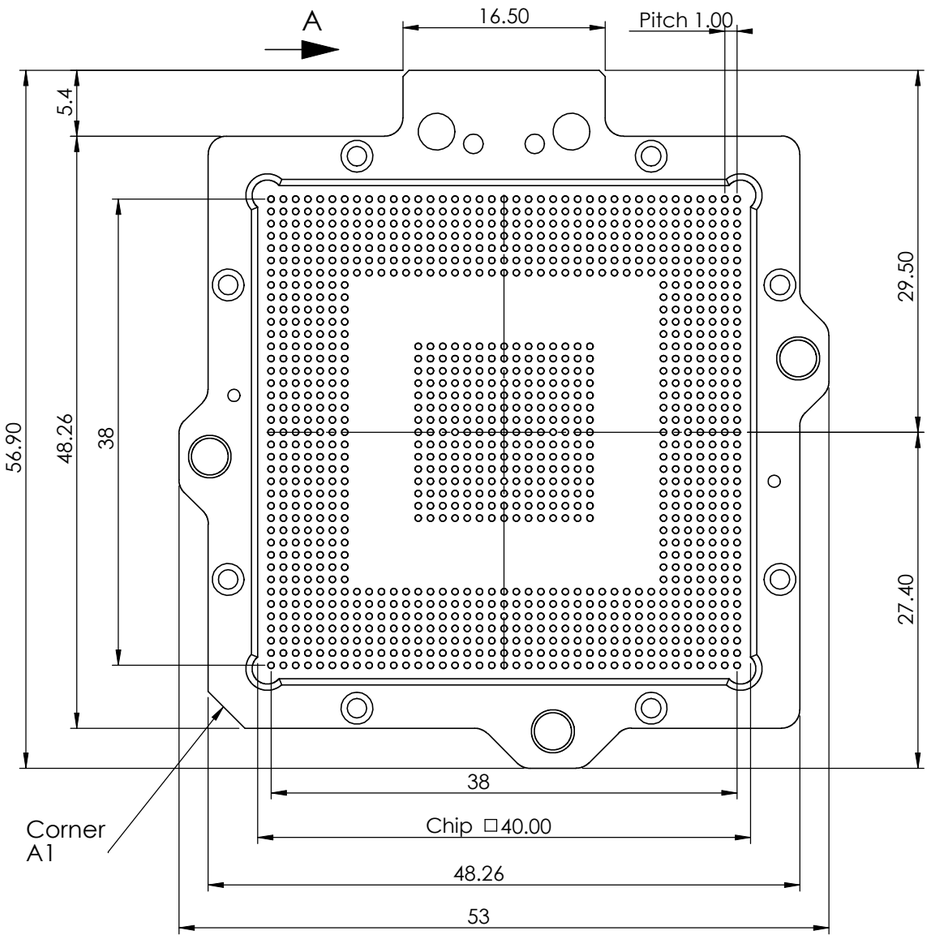


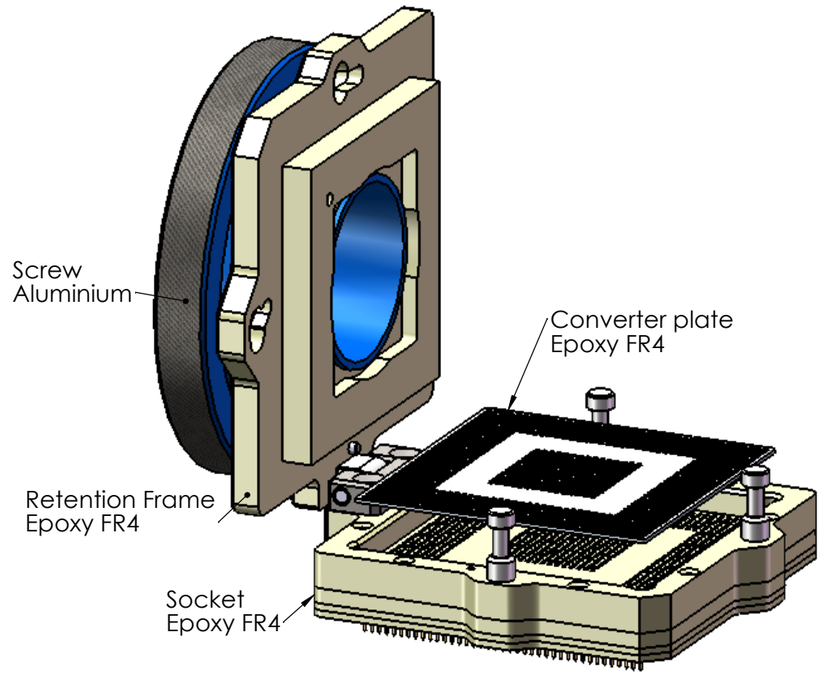


RETENTION FRAME

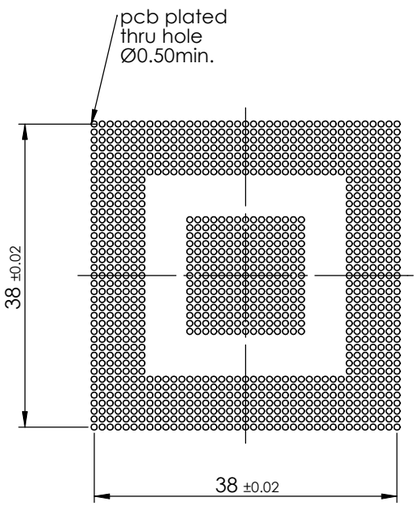


CONVERTER PLATE





Socket designed for chip
LGA 1.3 to 3.8 thickness without die
BGA 1.3 to 3.3 thickness with balls and without die



PCB LAYOUT

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
SURFACE FINISH:
GENERAL TOLERANCES ISO 2768m

Remark: BGA/LGA Economic Clamshell socket,
1121 pins,Pitch 1.00mm, matrix 39x39
Retention frame
code AB= Opening 25.5x25.5 on Low profile

Patented		Visa	Date	Drawn by	Date	Visa
DRAWN		sme	02.09.2010	sme	02.09.2010	
CHK'D						
APPV'D		sme	02.09.2010			

Echelle: 2:1

MATERIAL: .

WEIGHT:

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"E-tec order code" **LPE1121-1070-39AB95C** A3H

"Production code" LPE1121-10-09415-39ABA-C

0 Revision

SHEET 1 OF 1